
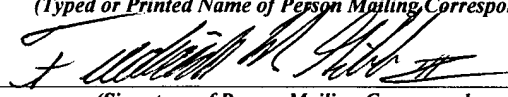


IFW

<b>CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)</b> Applicant(s): Arvelo et al.			Docket No. FIS920030258	
Application No. 10/672,494	Filing Date September 26, 2003	Examiner Unknown	Customer No. 29154	Group Art Unit 3753
Invention: <b>METHOD AND STRUCTURE FOR COOLING A DUAL CHIP MODULE WITH ONE HIGH POWER CHIP</b>				
<div></div>				
<p>I hereby certify that this <u>Submission of Replacement Drawing Sheets</u> (Identify type of correspondence)</p> <p>is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on <u>01/25/05</u> (Date)</p> <p><u>Frederick W. Gibb, III</u> (Typed or Printed Name of Person Mailing Correspondence)  (Signature of Person Mailing Correspondence)</p> <p>Note: Each paper must have its own certificate of mailing.</p> <div></div>				



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Arvelo et al.

Serial No.: 10/672,494

Group Art Unit: 3753

Filed: September 26, 2003

Examiner: Unknown

For: METHOD AND STRUCTURE FOR COOLING A DUAL CHIP MODULE WITH ONE  
HIGH POWER CHIP

Commissioner of Patents  
PO BOX 1450  
Alexandria, VA 22313-1450

**SUBMISSION OF REPLACEMENT DRAWING SHEETS**

Sir:

Submitted herewith are five sheets of replacement drawing sheets comprising Figures 1-11.  
Please replace the drawings originally filed with the accompanying replacement sheets. Approval  
and acknowledgment of receipt are respectfully requested.

Respectfully Submitted,

Frederick W. Gibb, III  
Reg. No. 37,629

Date: 1-25-05  
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